

UP04534

Silicon NPN epitaxial planar type

For high-frequency amplification

■ Features

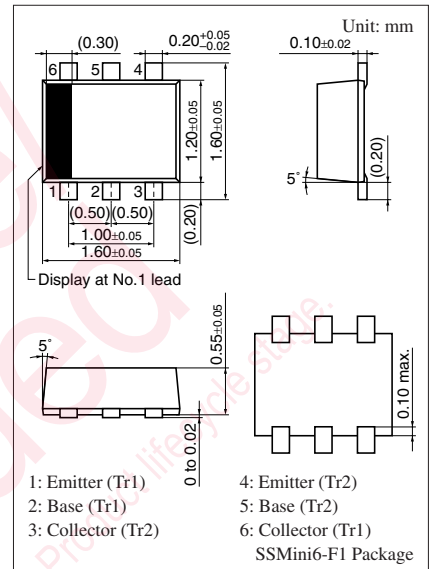
- Two elements incorporated into one package (Each transistor is separated)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

- 2SC2404 × 2

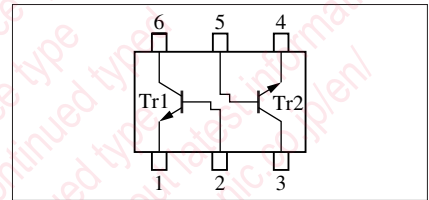
■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	30	V
Collector-emitter voltage (Base open)	V_{CEO}	20	V
Emitter-base voltage (Collector open)	V_{EBO}	3	V
Collector current	I_{C}	15	mA
Total power dissipation	P_{T}	125	mW
Junction temperature	T_{j}	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$



Marking Symbol: 7E

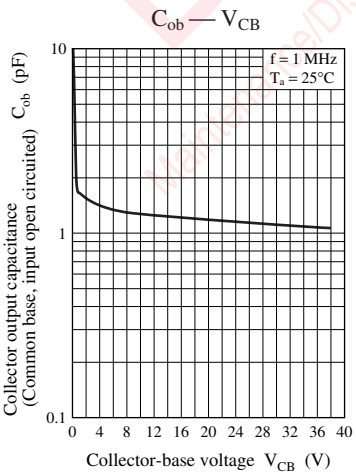
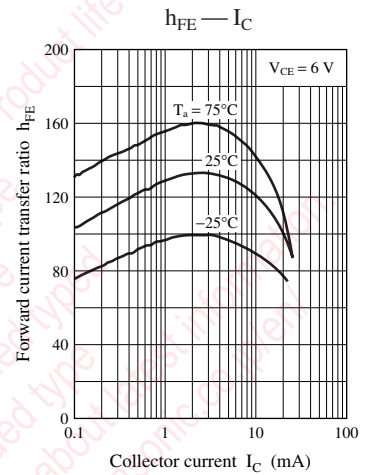
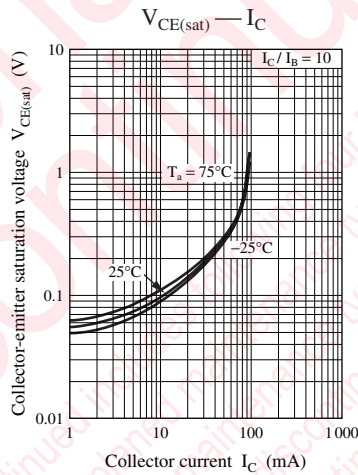
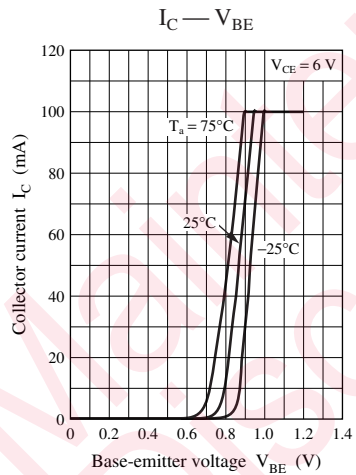
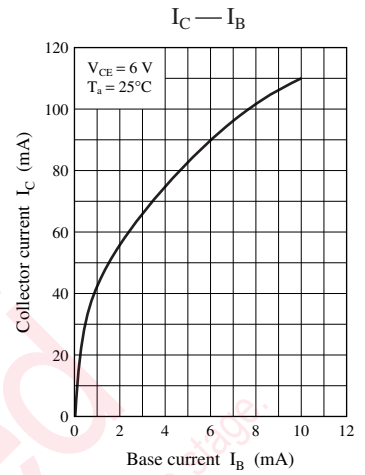
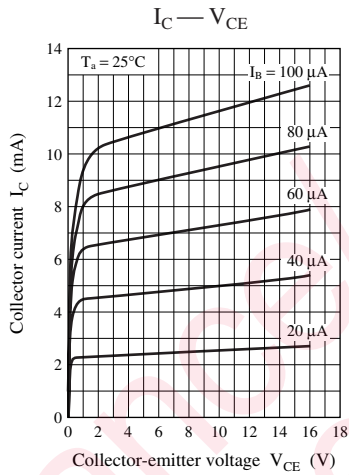
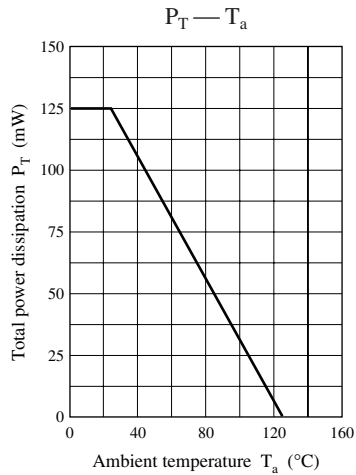
Internal Connection



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\text{C}} = 10 \mu\text{A}$, $I_{\text{E}} = 0$	30			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_{\text{E}} = 10 \mu\text{A}$, $I_{\text{C}} = 0$	3			V
Base-emitter voltage	V_{BE}	$V_{\text{CB}} = 6 \text{ V}$, $I_{\text{E}} = -1 \text{ mA}$		720		mV
Forward current transfer ratio	h_{FE}	$V_{\text{CB}} = 6 \text{ V}$, $I_{\text{E}} = -1 \text{ mA}$	65		160	—
Reverse transfer capacitance (Common emitter)	C_{re}	$V_{\text{CB}} = 6 \text{ V}$, $I_{\text{E}} = -1 \text{ mA}$, $f = 10.7 \text{ MHz}$		0.8	1.0	pF
Transition frequency	f_{T}	$V_{\text{CB}} = 6 \text{ V}$, $I_{\text{E}} = -1 \text{ mA}$, $f = 200 \text{ MHz}$	450	650		MHz
Noise figure	NF	$V_{\text{CB}} = 6 \text{ V}$, $I_{\text{E}} = -1 \text{ mA}$, $f = 100 \text{ MHz}$		3.3		dB
Power gain	G_{p}	$V_{\text{CB}} = 6 \text{ V}$, $I_{\text{E}} = -1 \text{ mA}$, $f = 100 \text{ MHz}$		24		dB

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.



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